

	Type	L #	Hits	Search Text	DBs	Comments
1	BRS	L1	153543	438/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
2	BRS	L2	2156	1 and (cu or copper) near (interconnect\$3 or damascene)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
3	BRS	L3	102	2 and (cu or copper) near electromigration	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
4	BRS	L4	0	3 and (Al or aluminum) near (dopant near (layer or film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
5	BRS	L5	4	3 and (dopant near (layer or film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
6	BRS	L6	10	(marieb-thomas-n or Mcgregor-paul or block-carolyn or jin-shu).in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
7	BRS	L7	3	6 and (cu or copper) near electromigration	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
8	BRS	L8	718	((cu or copper) near (interconnect\$3 or damascene)).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
9	BRS	L10	2	9 and (dopant near (layer or film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
10	BRS	L9	16	8 and electromigration.ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
11	BRS	L11	5079	((cu or copper) near (interconnect\$3 or damascene))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
12	BRS	L12	155	11 and (cu or copper) near electromigration	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
13	BRS	L13	1	12 and (Al or aluminum) near dopant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
14	BRS	L14	4	12 and (Al or aluminum) near dop\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	